

MOSFET - Power, Single N-Channel, SOT-23 20 V, 3.2 A

NTR4501N, NVR4501N

Features

- Leading Planar Technology for Low Gate Charge / Fast Switching
- 2.5 V Rated for Low Voltage Gate Drive
- SOT-23 Surface Mount for Small Footprint
- NVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Load/Power Switch for Portables
- Load/Power Switch for Computing
- DC-DC Conversion

MAXIMUM RATINGS (T_J= 25°C unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	20	V
Gate-to-Source Voltage			V _{GS}	±12	V
Continuous Drain	ontinuous Drain Steady State $T_A = 25^{\circ}C$ $T_A = 85^{\circ}C$		I _D	3.2	Α
Current (Note 1)				2.4	Α
Steady State Power Dissipation (Note 1)	Steady State		P _D	1.25	W
Pulsed Drain Current	t _p = 10 μs		I _{DM}	10.0	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Continuous Source Current (Body Diode)			Is	1.6	Α
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	100	°C/W
Junction-to-Ambient (Note 2)	$R_{\theta JA}$	300	

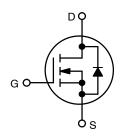
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).
- 2. Surface-mounted on FR4 board using the minimum recommended pad size.

1

V _{(BR)DSS}	R _{DS(on)} Typ	I _D Max (Note 1)
20 V	70 mΩ @ 4.5 V	3.6 A
	88 mΩ @ 2.5 V	3.1 A

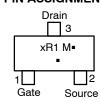
N-Channel



SOT-23

CASE 318 STYLE 21

MARKING DIAGRAM & PIN ASSIGNMENT



TR1 = Device Code for NTR4501N VR1 = Device Code for NVR4501N

= Date Code* = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NTR4501NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NVR4501NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
OFF CHARACTERISTICS	-		-	-	-	-
Drain-to-Source Breakdown Voltage (Note 3)	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu A$	20	24.5		V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J			22		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, T _J = 25°C			1.5	μΑ
		V _{DS} = 16 V, T _J = 85°C			10	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage (Note 3)	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	0.65		1.2	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J			-2.3		mV/°C
Drain-to-Source On Resistance	_	V _{GS} = 4.5 V, I _D = 3.6 A		70	80	mΩ
	R _{DS(on)}	V _{GS} = 2.5 V, I _D = 3.1 A		88	105	
Forward Transconductance	9FS	V _{DS} = 5.0 V, I _D = 3.6 A		9		S
CHARGES AND CAPACITANCES						
Input Capacitance	C _{iss}			200		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,} $ $V_{DS} = 10 \text{ V}$		80		
Reverse Transfer Capacitance	C _{rss}	TDS 15 1		50		
Total Gate Charge	Q _{G(TOT)}			2.4	6.0	nC
Gate-to-Source Gate Charge	Q _{GS}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V},$ $I_{D} = 3.6 \text{ A}$		0.5		7
Gate-to-Drain Charge	Q_{GD}	.5 5.571		0.6		
SWITCHING CHARACTERISTICS (Note 4)						
Turn-On Delay Time	t _{d(on)}			6.5	13	ns
Rise Time	t _r	V _{GS} = 4.5 V, V _{DS} = 10 V,		12	24	
Turn-Off Delay Time	t _{d(off)}	$I_D = 3.6 \text{ A}, R_G = 6.0 \Omega$		12	24	
Fall Time	t _f			3	6	
SOURCE-DRAIN DIODE CHARACTERISTICS	3					
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V, I _{SD} = 1.6 A		0.8	1.2	V
Reverse Recovery Time	t _{RR}			7.1		ns
Charge Time	ta	$V_{GS} = 0 V$		5		1
Discharge Time	t _b	$d_{IS}/d_t = 100 \text{ A/}\mu\text{s},$ $I_S = 1.6 \text{ A}$		1.9		1
Reverse Recovery Charge	Q_{RR}			3.0	İ	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

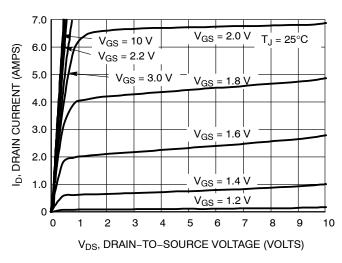
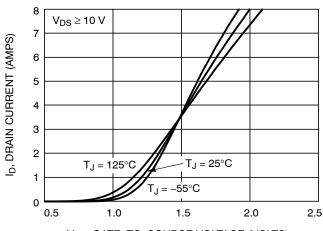


Figure 1. On-Region Characteristics



V_{GS}, GATE-TO-SOURCE VOLTAGE (VOLTS) Figure 2. Transfer Characteristics

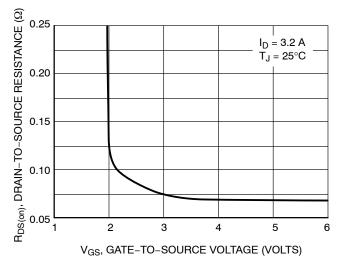


Figure 3. On-Resistance vs. Gate-to-Source Voltage

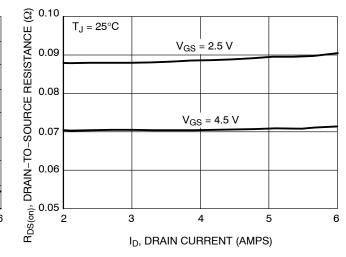


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

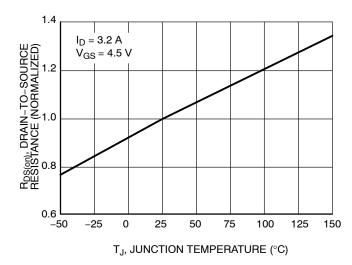
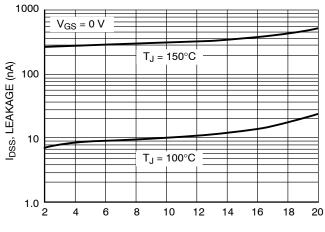


Figure 5. On–Resistance Variation with Temperature



V_{DS}, DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

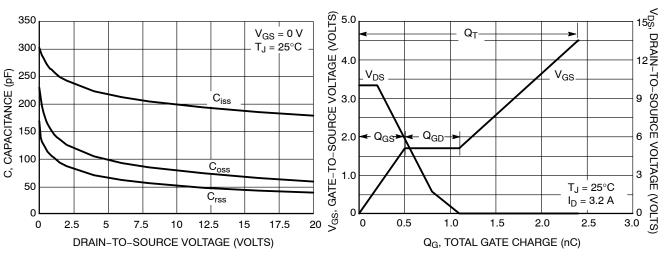


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

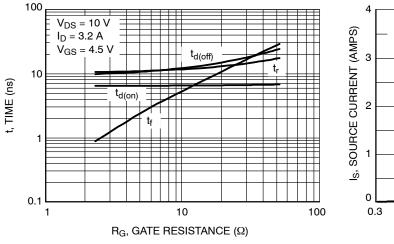


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

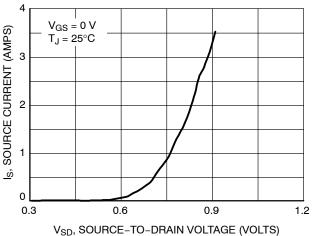


Figure 10. Diode Forward Voltage vs. Current

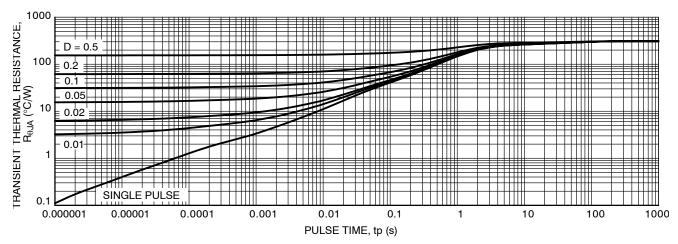


Figure 11. Thermal Response

TYPICAL CHARACTERISTICS

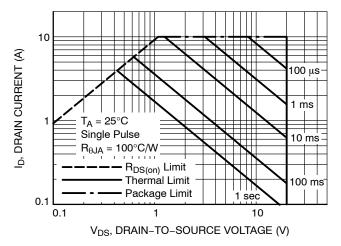


Figure 12. Safe Operating Area (SOA)

MILLIMETERS

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40





SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

DATE 14 AUG 2024

MAX

1.11

0.10

0.50

0.20

3.04

1.40

2.04

0.55

0.69

2.64

10°

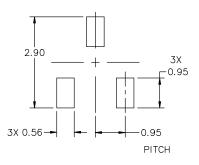




DETAIL "A" Scale 3:1







NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR			
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	2. CATHODE 2.	2: STYLE 13: CATHODE PIN 1. SOURCE CATHODE 2. DRAIN ANODE 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	2. ANODE 2.	3: STYLE 19: NO CONNECTION PIN 1. CATHODE CATHODE 2. ANODE ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT			STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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